



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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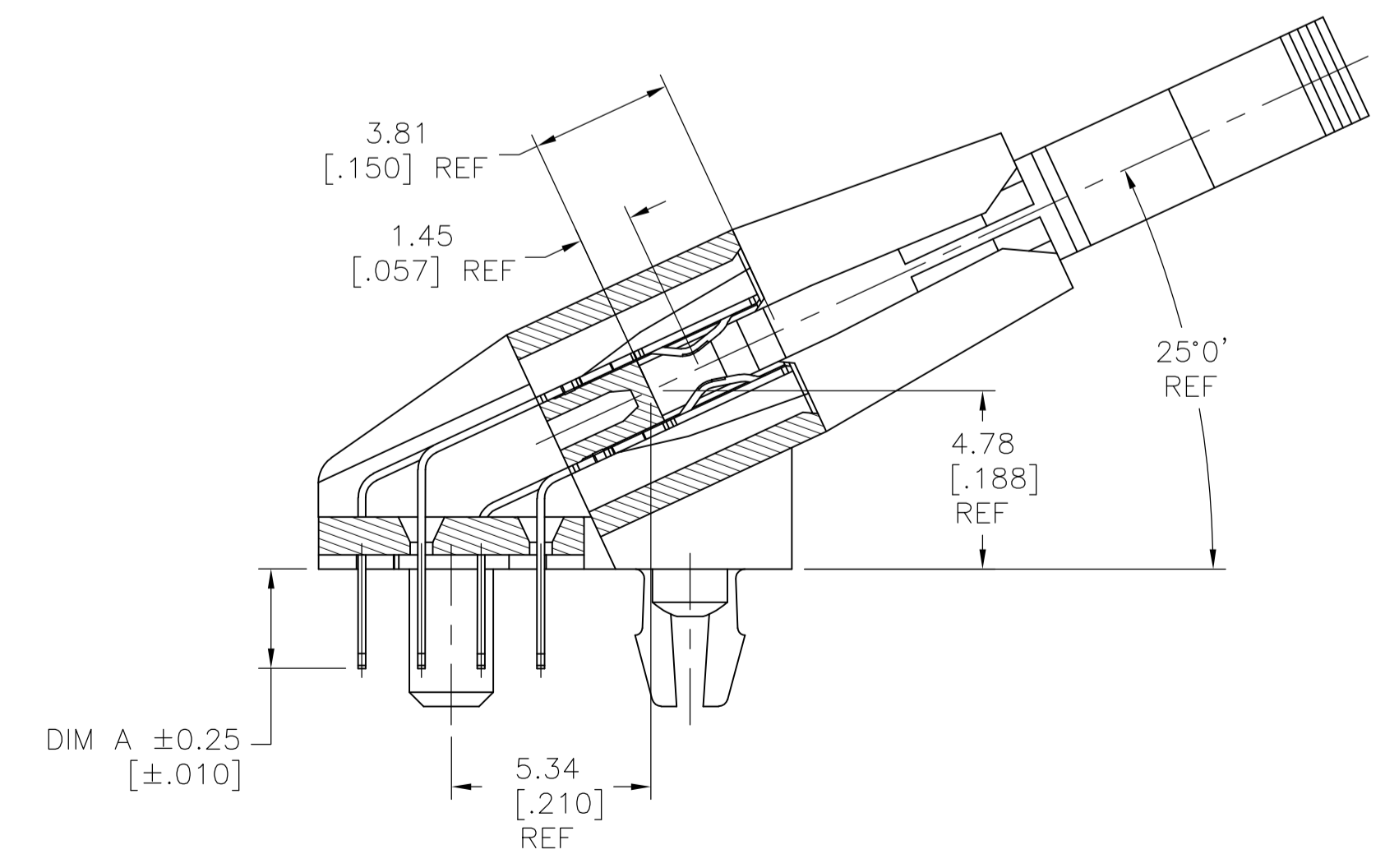
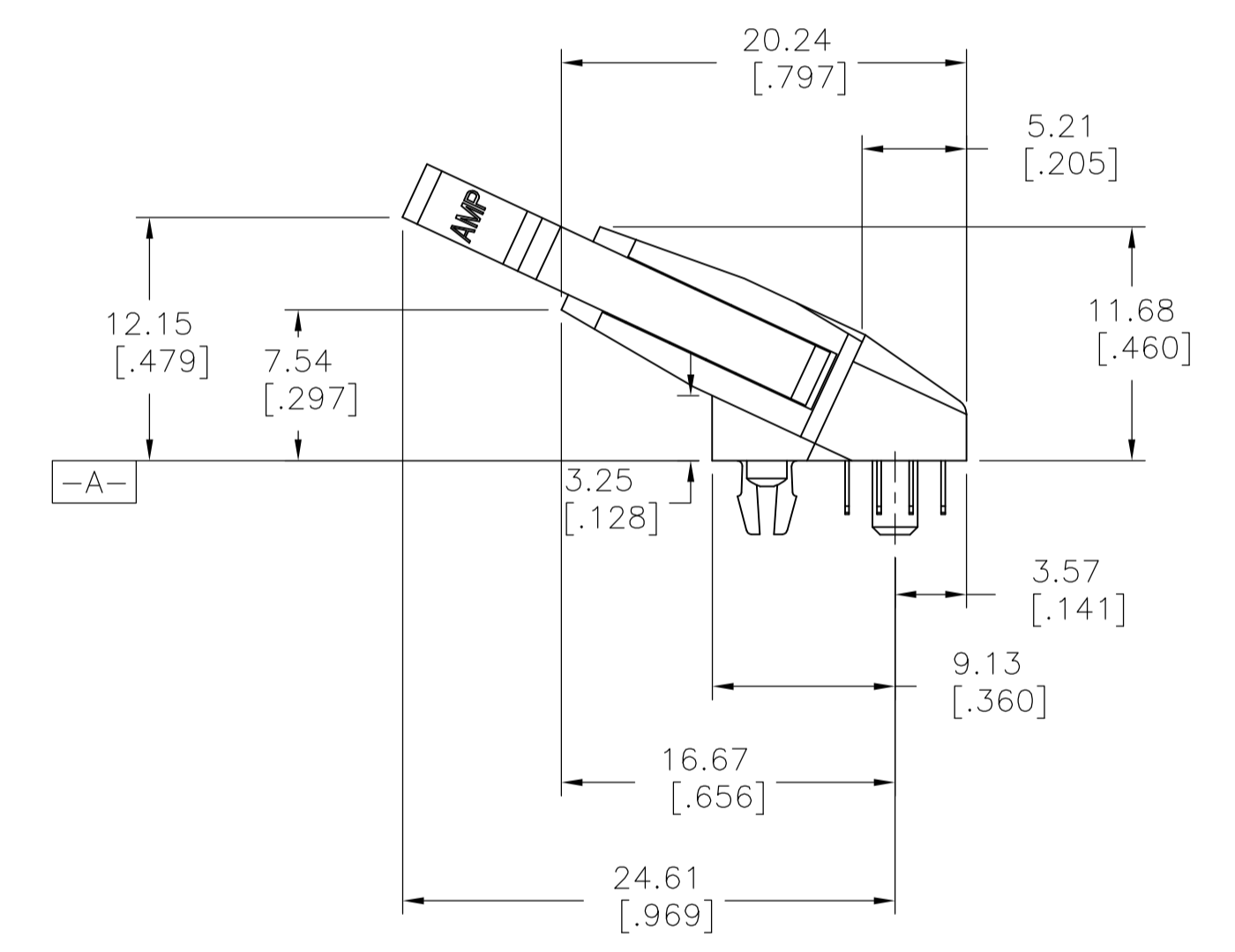
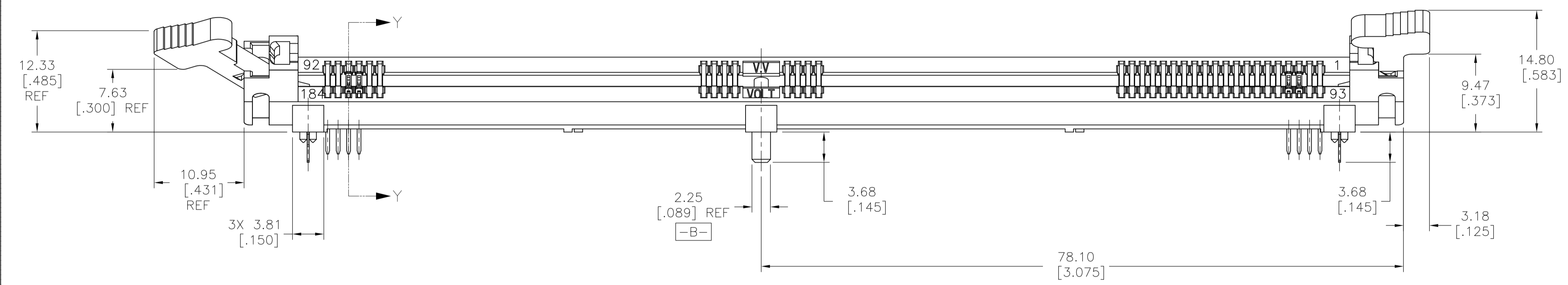
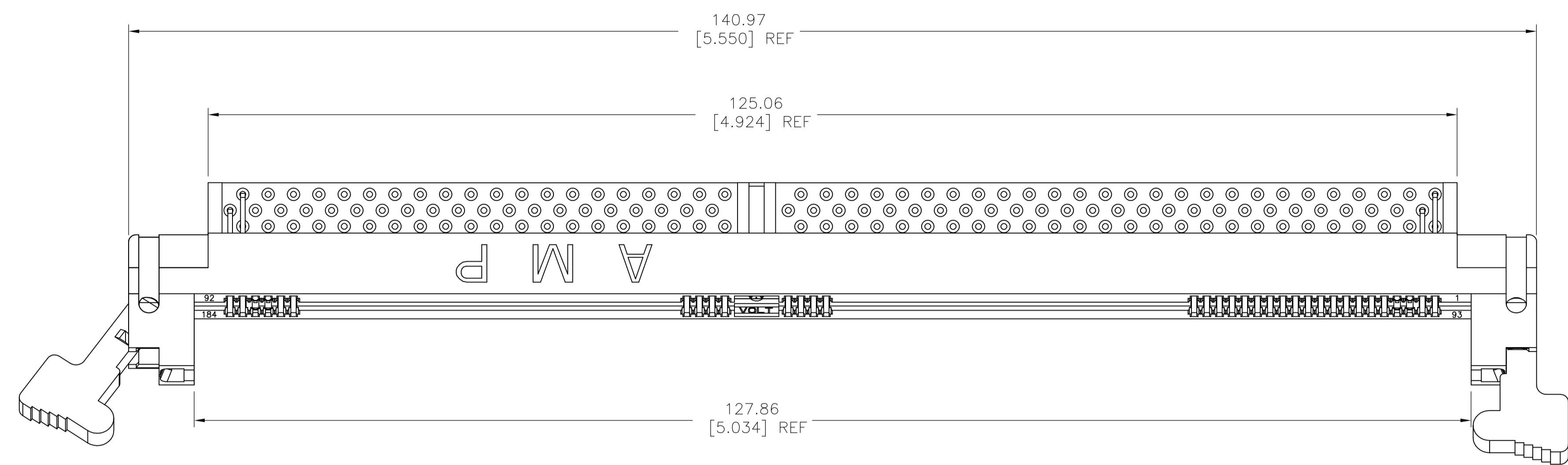
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		DIST		REVISIONS			
GP	00	REV	DATE	BY	CHK	APP	
A		REVISED PER EC OS11-0009-05	08APR05	BM		MY	
A1		REVISED PER ECO-10-000444	04NOV09	KK		AEG	

- MATERIAL:
HOUSING AND EJECTOR:
HIGH TEMPERATURE NYLON
CONTACT:
PHOSPHOR BRONZE
 - FINISH:
CONTACT AREA:
0.000760[.000030] MIN GOLD OVER
0.001270[.000050] MIN THICK NICKEL
SOLDER TAIL:
0.00381[.000150] MIN THICK MATTE TIN OVER
0.000641[.000025] MIN THICK NICKEL
 - MODULE BOARD PADS:
FOR OPTIMUM PERFORMANCE PADS SHOULD BE SMOOTH AND FLAT
PADS TO BE PLATED WITH:
0.00102[.000040] MIN THICK GOLD OVER
0.00127[.000050] MIN THICK NICKEL
- 4 PN: 5390402-6 IS THE SAME CONNECTOR AS 5390402-3 WITH LUBRICANT ADDED TO THE CONTACTS.
- 5 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SECTION Y-Y
SCALE 6:1

DIM A	KEY POSITIONS	DESCRIPTION	PART NUMBER
4.50 [.177]	DETAIL B	184 POSN. DDR, 2.5V	5390402-7
3.18 [.125]	DETAIL B	184 POSN. DDR, 2.5V	5390402-6 4
3.18 [.125]	DETAIL A	184 POSN. DDR, 1.8V	5390402-4
3.18 [.125]	DETAIL B	184 POSN. DDR, 2.5V	5390402-3
2.62 [.103]	DETAIL A	184 POSN. DDR, 1.8V	5390402-2
2.62 [.103]	DETAIL B	184 POSN. DDR, 2.5V	5390402-1

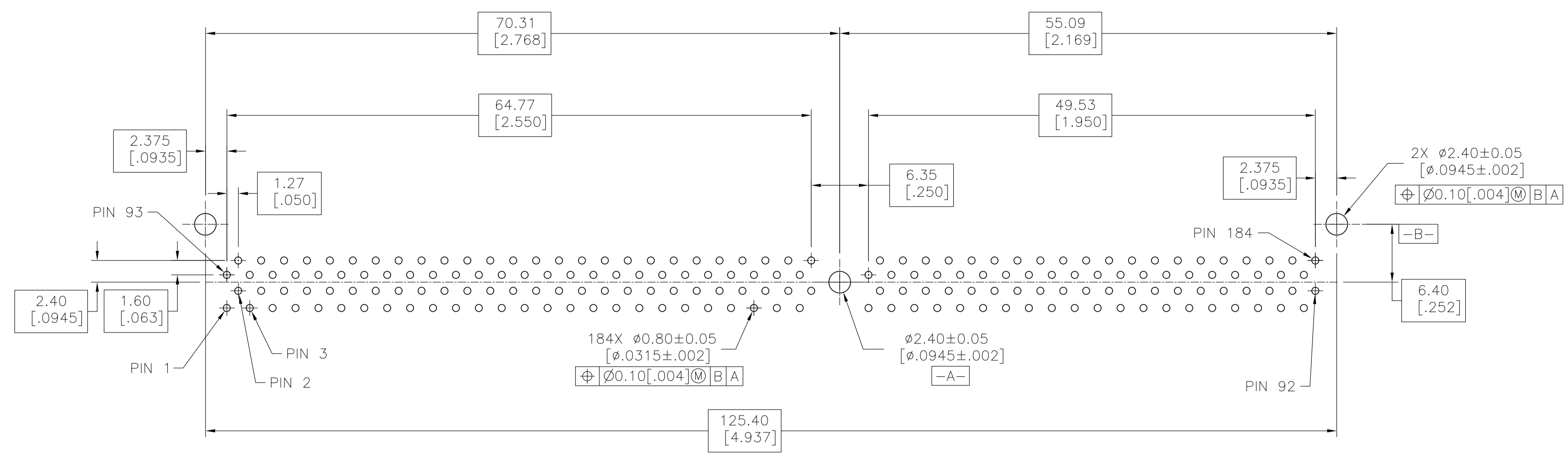
THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	0 PLC ± -	1 PLC ± -	2 PLC ± 0.13[.005]	3 PLC ± -	4 PLC ± -	ANGLES ± -
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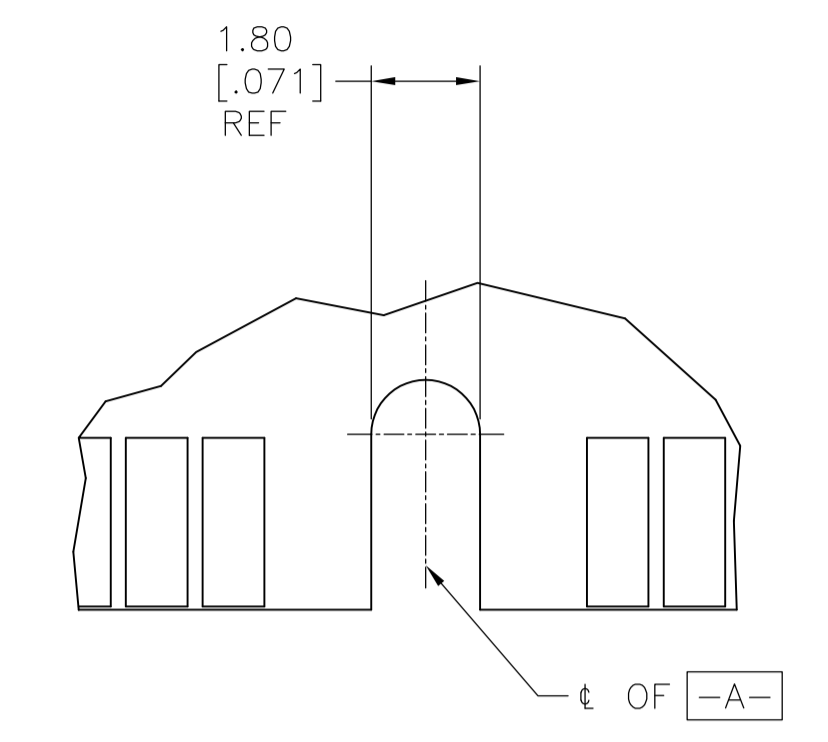
MATERIAL	FINISH	WEIGHT	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
			A1	00779	5390402	

CUSTOMER DRAWING SCALE 3:1 SHEET 1 OF 3 REV A1

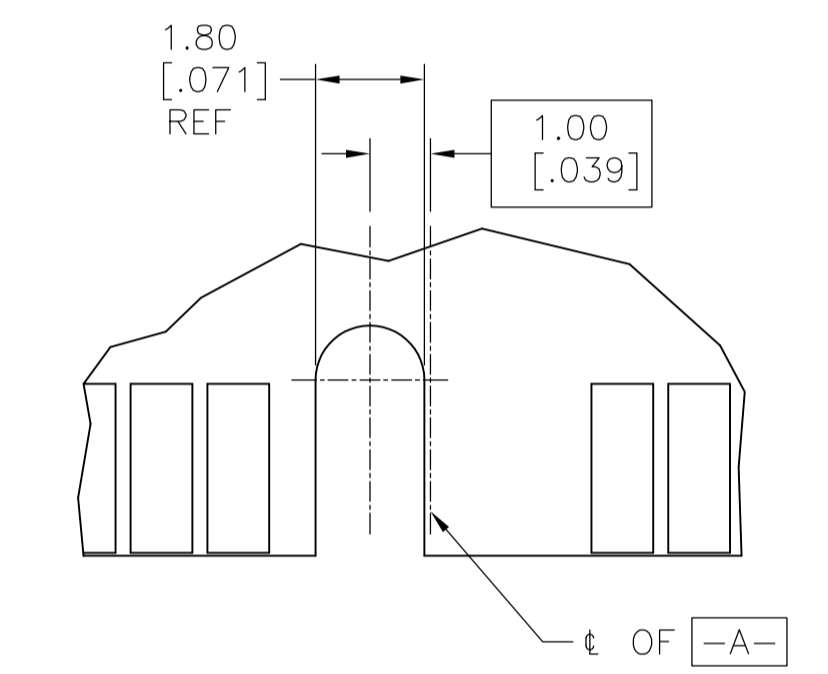
LOC		DIST		REVISIONS				
GP	00	P	LTR	DESCRIPTION	DATE	DN	APVD	
				SEE SHEET 1				



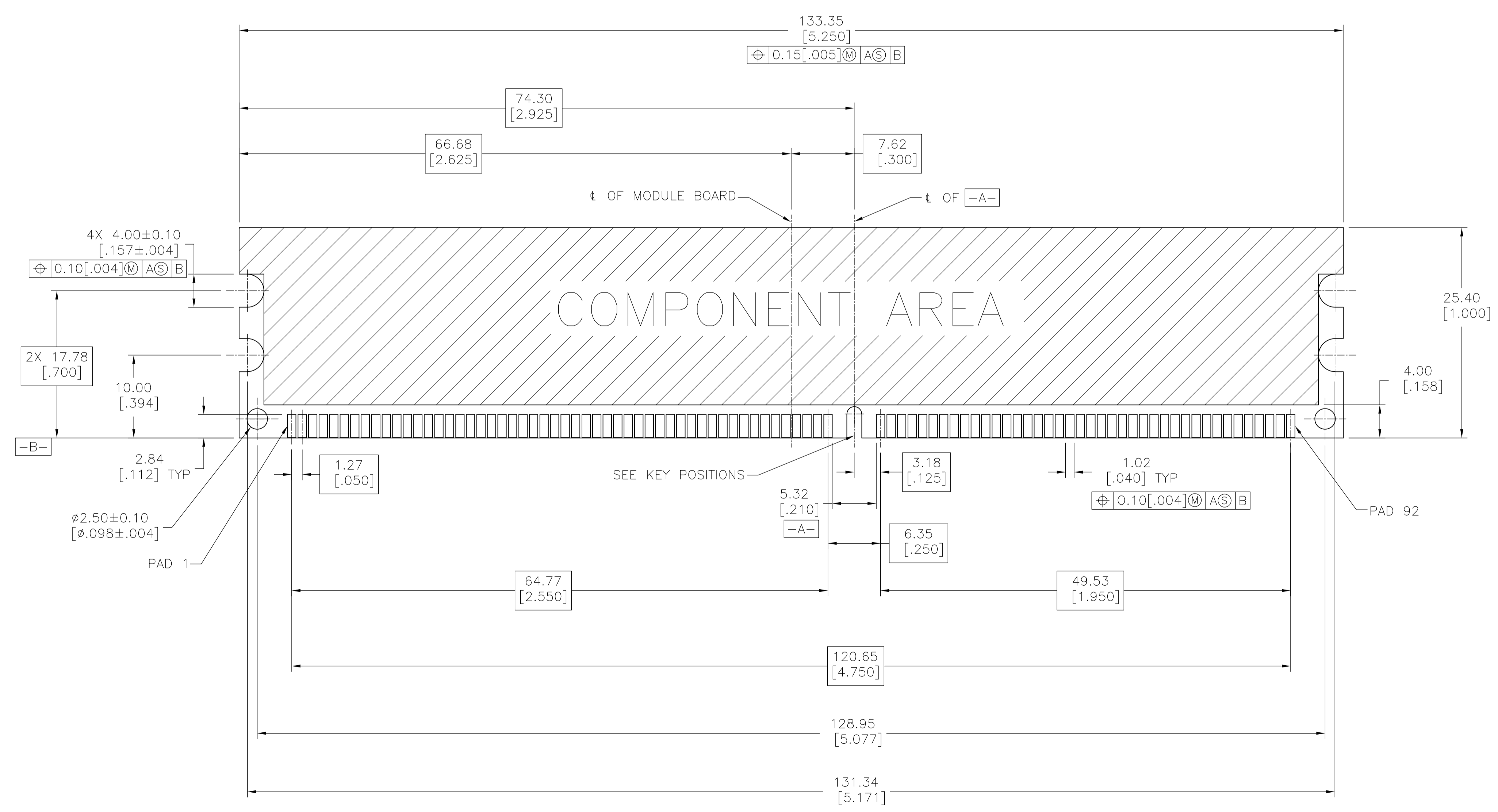
RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



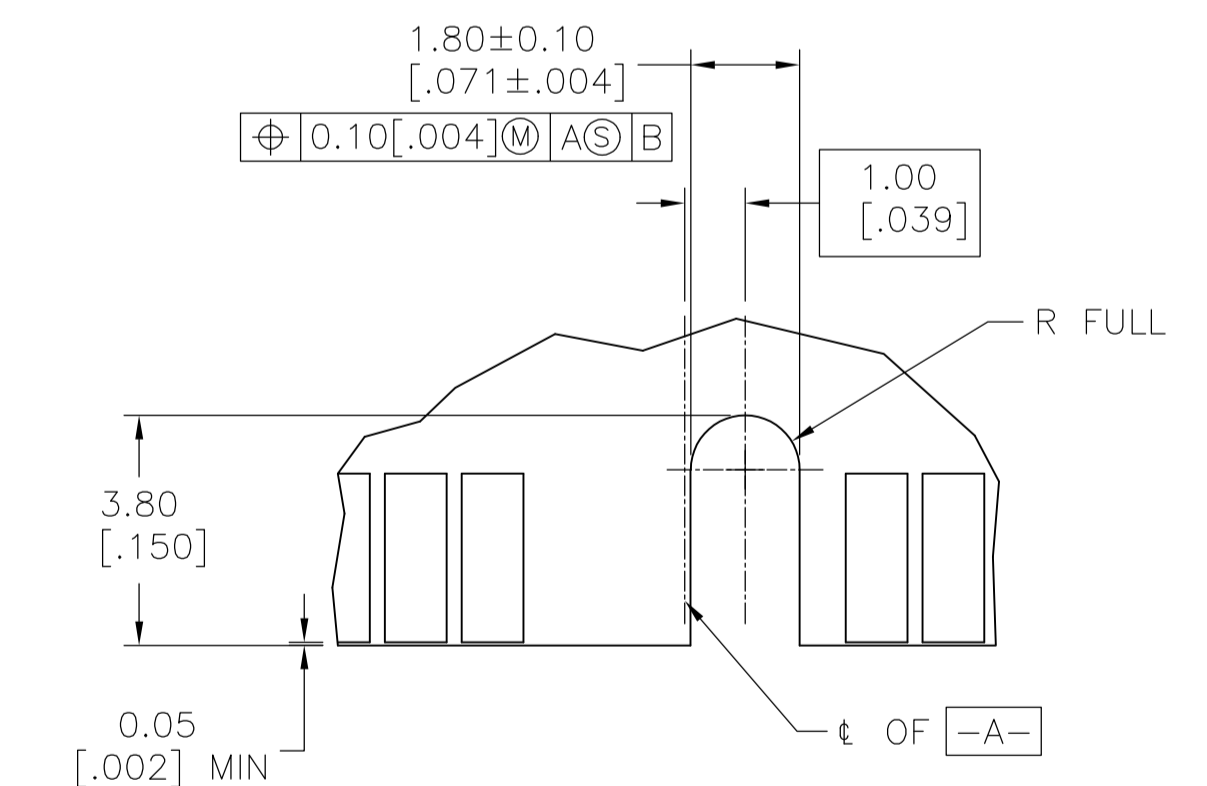
DETAIL A SCALE 8:1



DETAIL B SCALE 8:1



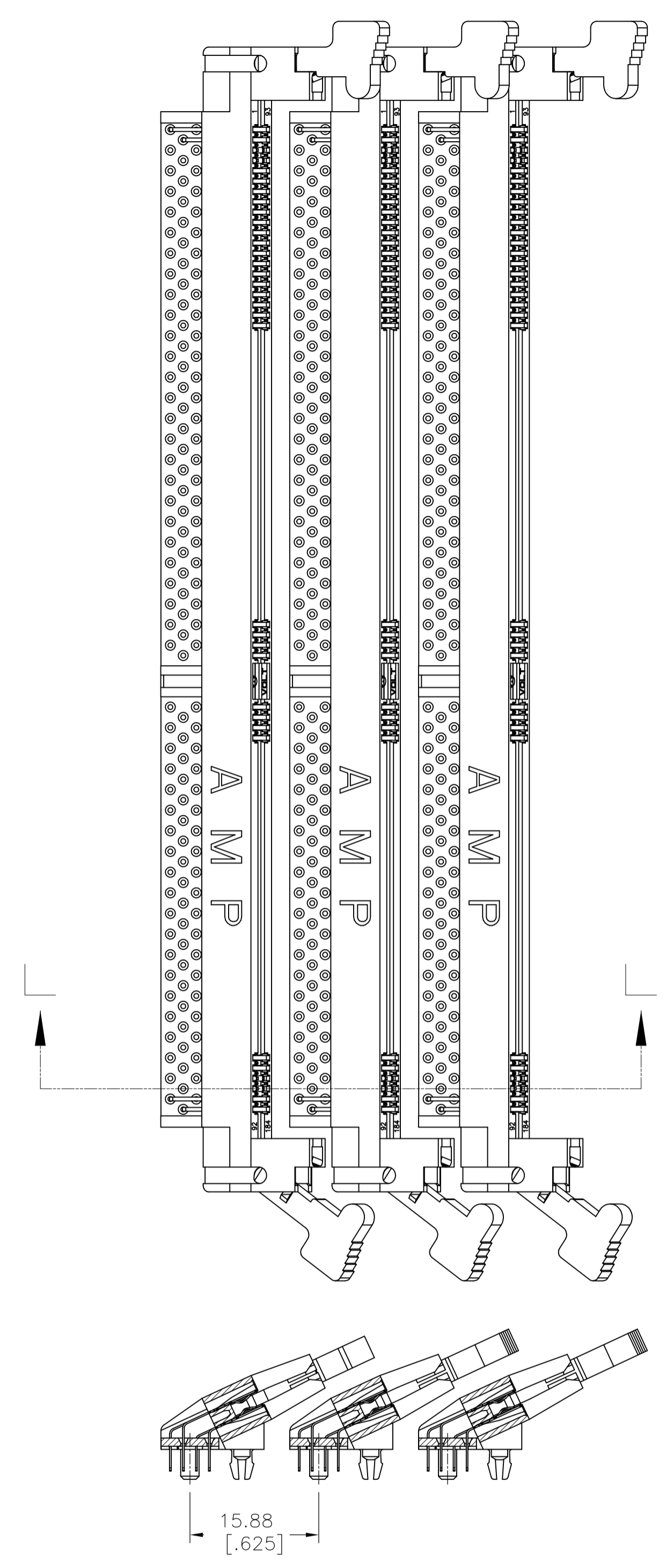
RECOMMENDED MODULE LAYOUT



DETAIL C SCALE 8:1

KEY POSITIONS

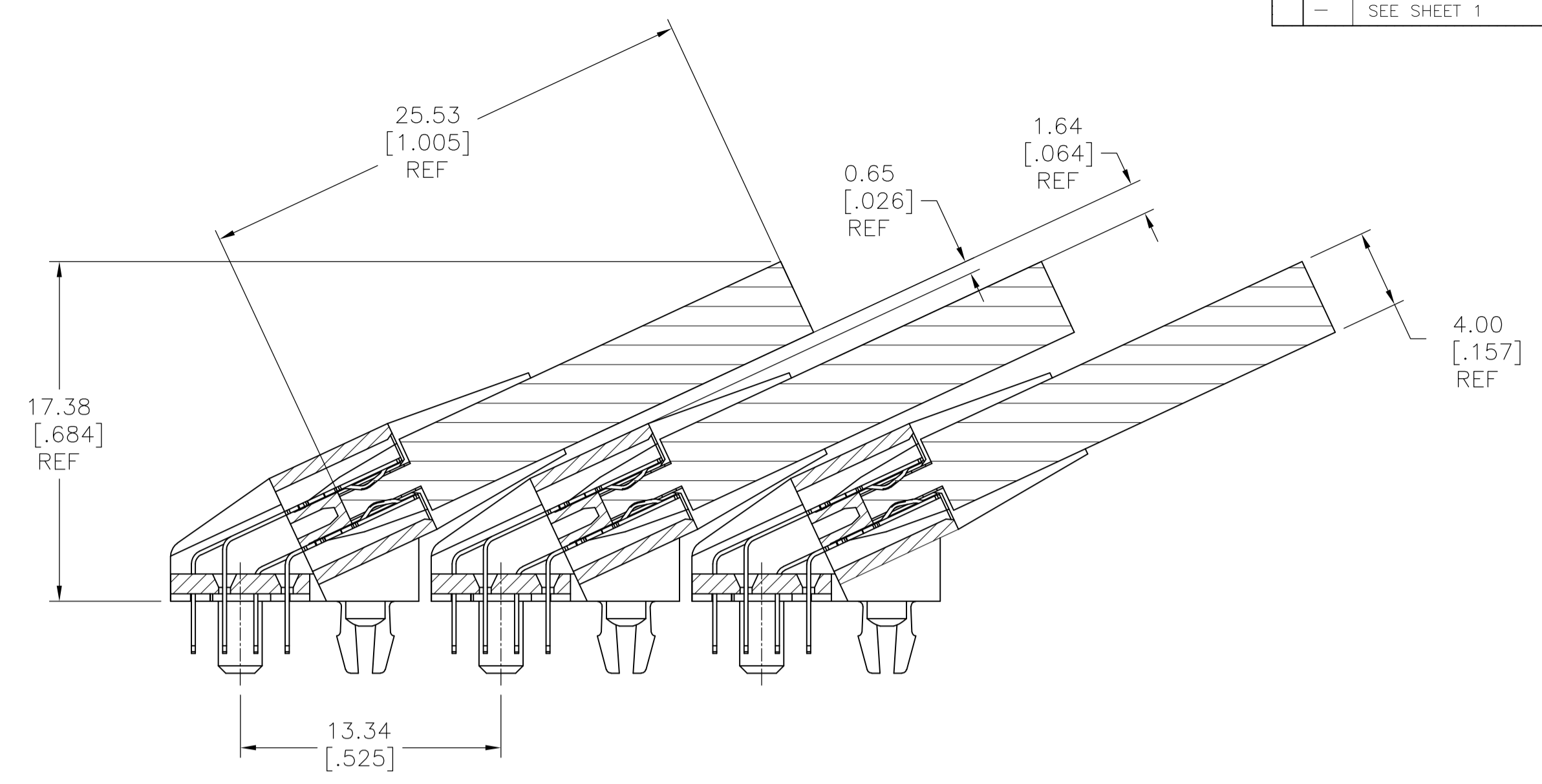
THIS DRAWING IS A CONTROLLED DOCUMENT.		DN S. WAITMAN 11OCT04	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
DIMENSIONS: mm		CHK M. YFOMANS 11OCT04	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPD M. YFOMANS 11OCT04	NAME
0 PL	±		SIZE
1 PL	±		CAGE CODE
2 PL	±		DRAWING NO
3 PL	± 0.13 [.005]		RESTRICTED TO
4 PL	±		WEIGHT
ANGLES	±		A1 00779 C=5390402
MATERIAL	FINISH	SCALE 3:1	SHEET 2 OF 3
		CUSTOMER DRAWING	REV A1



SECTION L-L
SCALE 2:1

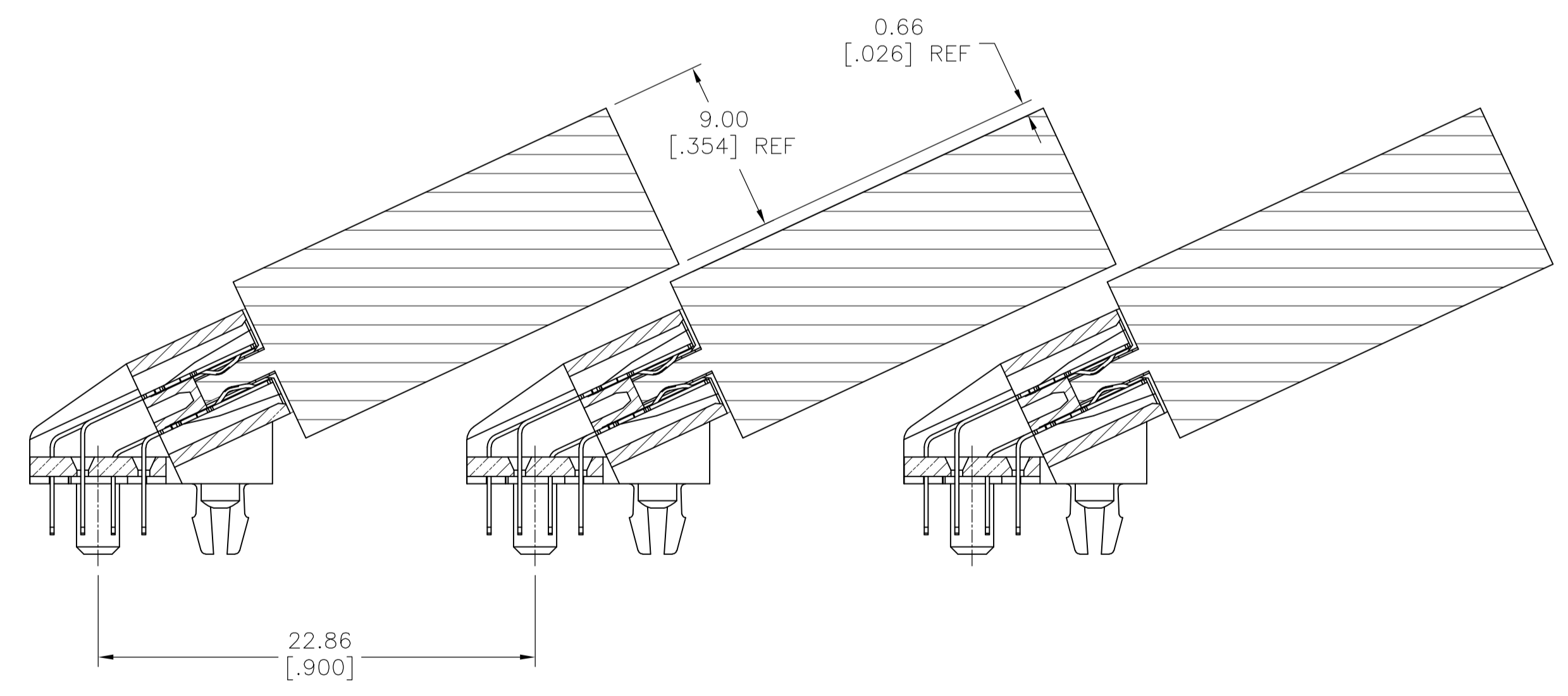
MINIMUM REPAIRABLE
SOCKET TO SOCKET REPAIRING

WITH THE MODULES REMOVED SOCKETS ON 15.88[.625] OR GREATER SPACING CAN BE INDIVIDUALLY UNSOLDERED FROM THE BOARD AND REMOVED IF NECESSARY



MINIMUM SOCKET TO SOCKET SPACING

WITH A 4.00[.158] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34[.525] WILL LEAVE APPROXIMATELY 0.65[.026] OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



POSSIBLE SOCKET TO SOCKET SPACING FOR 9MM MODULE

WITH A 9.00[.355] WIDE MODULE BOARD; A SOCKET TO SOCKET SPACING OF 22.86[.900] WILL LEAVE APPROXIMATELY 0.66[.026] CLEARANCE BETWEEN THE ADJACENT MODULES. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DN S. WAITMAN 11OCT04	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm		CHK M. YFOMANS 11OCT04	NAME SOCKET ASSEMBLY, 184 POS, DDR LOW PROFILE DIMM2P, LEAD FREE	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0. PLC ± - 1. PLC ± - 2. PLC ± 0.13[.005] 3. PLC ± - 4. PLC ± - ANGLES ± -		APPD M. YFOMANS 11OCT04	PRODUCT SPEC APPLICATION SPEC	
MATERIAL		FINISH	SIZE A1	RESTRICTED TO
		WEIGHT	CAGE CODE 00779	DRAWING NO 5390402
		CUSTOMER DRAWING	SCALE 4:1	SHEET 3 OF 3